

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**Sx02xS Series**



**Main Features**

Symbol	Value	Unit
$I_{T(RMS)}$	1.5	A
$V_{DRM}/V_{RRM}$	400 to 600	V
$I_{GT}$	200	$\mu A$

**Applications**

The Sx02xS EV series is specifically designed for Gas Ignition applications that require high pulse surge current capability.

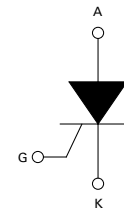
**Description**

New 1.5 Amp sensitive gate SCR series offers high static dv/dt with low turn off time (tq) through small die planar construction design. All SCR's junctions are glass-passivated to ensure long term reliability and parametric stability.

**Features**

- RoHS compliant and Halogen-Free
- Thru hole and surface mount packages
- Surge capability > 15Amps
- Blocking voltage ( $V_{DRM}/V_{RRM}$ ) capability — up to 600V
- High dv/dt noise immunity
- Improved turn-off time (tq) < 35  $\mu sec$ .
- Sensitive gate for direct microprocessor interface

**Schematic Symbol**



**Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit	
$I_{T(RMS)}$	RMS on-state current (full sine wave)	TO-92 $T_c = 65^\circ C$	1.5	A
		SOT-223 $T_L = 95^\circ C$		
$I_{T(AV)}$	Average on-state current	TO-92 $T_c = 65^\circ C$	0.95	A
		SOT-223 $T_c = 95^\circ C$		
$I_{TSM}$	Non repetitive surge peak on-state current (Single cycle, $T_j$ initial = $25^\circ C$ )	TO-92 $F = 50$ Hz	12.5	A
		SOT-223 $F = 60$ Hz		
$I^2t$	$I^2t$ Value for fusing	$t_p = 10$ ms $F = 50$ Hz	0.78	$A^2s$
		$t_p = 8.3$ ms $F = 60$ Hz		
di/dt	Critical rate of rise of on-state current $I_G = 10mA$	TO-92 $T_j = 125^\circ C$ SOT-223	50	$A/\mu s$
$I_{GM}$	Peak gate current	$t_p = 10$ $\mu s$ $T_j = 125^\circ C$	1.0	A
$P_{G(AV)}$	Average gate power dissipation	$T_j = 125^\circ C$	0.1	W
$T_{stg}$	Storage junction temperature range		-40 to 150	$^\circ C$
$T_j$	Operating junction temperature range		-40 to 125	$^\circ C$

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Description	Test Conditions	Sx02xS		Unit
			Min	Max	
$I_{GT}$	DC Gate Trigger Current	$V_D = 12\text{V}; R_L = 60\ \Omega$	15	200	$\mu\text{A}$
$V_{GT}$	DC Gate Trigger Voltage	$V_D = 12\text{V}; R_L = 60\ \Omega$	—	0.8	V
$V_{GRM}$	Peak Reverse Gate Voltage	$I_{RG} = 10\ \mu\text{A}$	5	—	V
$I_H$	Holding Current	$R_{GK} = 1\ \text{k}\Omega$	—	5	mA
(dv/dt)s	Critical Rate-of-Rise of Off-State Voltage	$T_J = 125^\circ\text{C}$ $V_D = V_{DRM} / V_{RRM}$ Exponential Waveform $R_{GK} = 1\ \text{k}\Omega$	25	—	V/ $\mu\text{s}$
$t_q$	Turn-Off Time	$T_J = 125^\circ\text{C} @ 600\ \text{V}$ $R_{GK} = 1\ \text{k}\Omega$	—	35	$\mu\text{s}$
$t_{gt}$	Turn-On Time	$I_G = 10\ \text{mA}$ PW = 15 $\mu\text{sec}$ $I_T = 3.0\ \text{A (pk)}$	—	3	$\mu\text{s}$

### Static Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Description	Test Conditions	Value		Unit
			Min	Max	
$V_{TM}$	Peak On-State Voltage	$I_{TM} = 3.0\ \text{A (pk)}$	—	1.70	V
$I_{DRM}$	Off-State Current, Peak Repetitive	$T_J = 25^\circ\text{C} @ V_D = V_{DRM}$ $R_{GK} = 1\ \text{k}\Omega$	—	5	$\mu\text{A}$
		$T_J = 125^\circ\text{C} @ V_D = V_{DRM}$ $R_{GK} = 1\ \text{k}\Omega$	—	500	$\mu\text{A}$

### Thermal Resistances

Symbol	Parameter		Value	Unit	
$R_{\theta(J-C)}$	Junction to case (AC)	$I_T = 1.5\ \text{A}_{(RMS)}^1$	TO-92	50	$^\circ\text{C/W}$
			SOT-223	25	
$R_{\theta(J-A)}$	Junction to ambient	$I_T = 1.5\ \text{A}_{(RMS)}^1$	TO-92	160	$^\circ\text{C/W}$
			SOT-223	60	

<sup>1</sup> 60Hz AC resistive load condition, 100% conduction.

### Additional Information



Datasheet

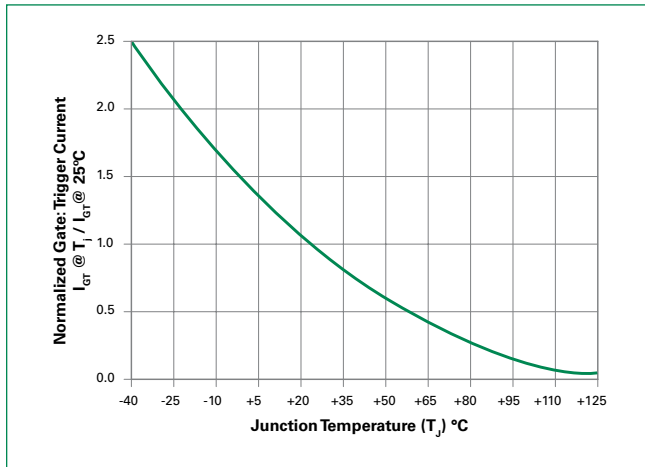


Resources

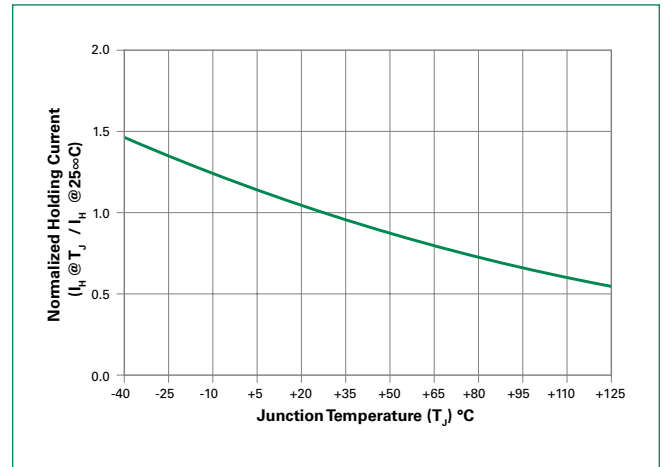


Samples

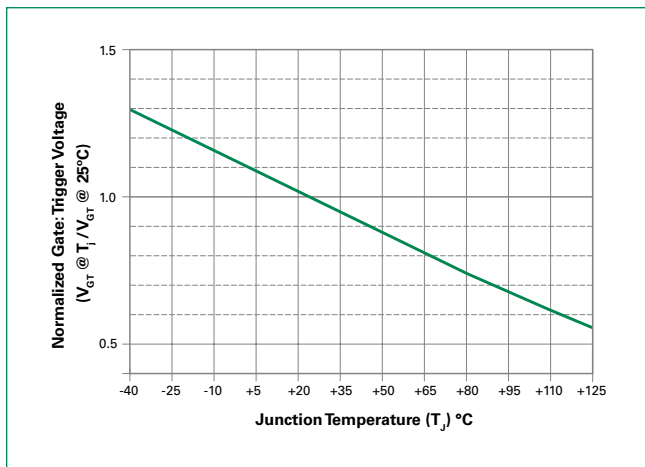
**Figure 1: Normalized DC Gate Trigger Current vs. Junction Temperature**



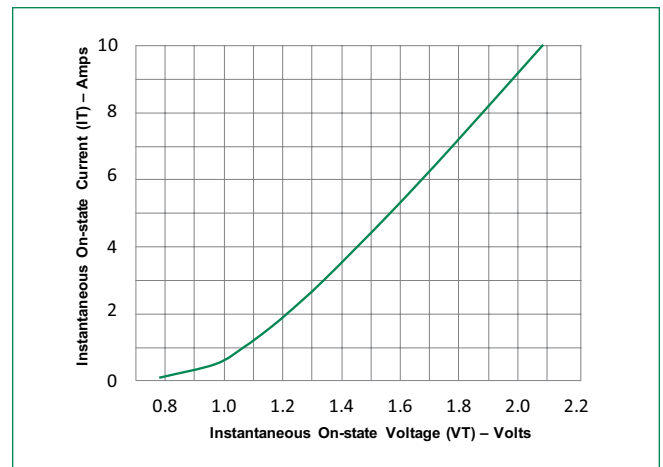
**Figure 2: Normalized DC Holding Current vs. Junction Temperature**



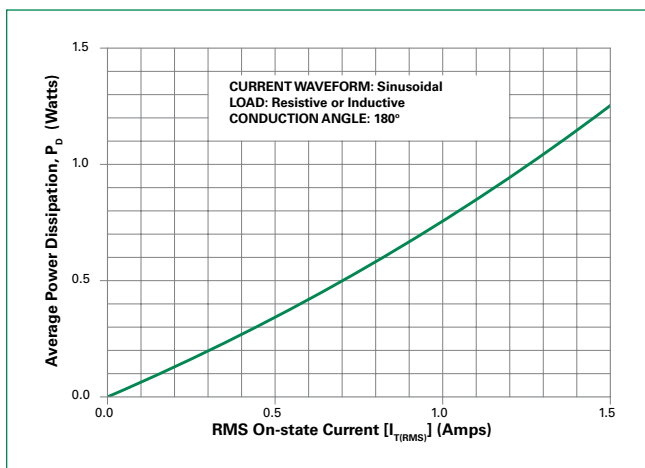
**Figure 3: Normalized DC Gate Trigger Voltage vs. Junction Temperature**



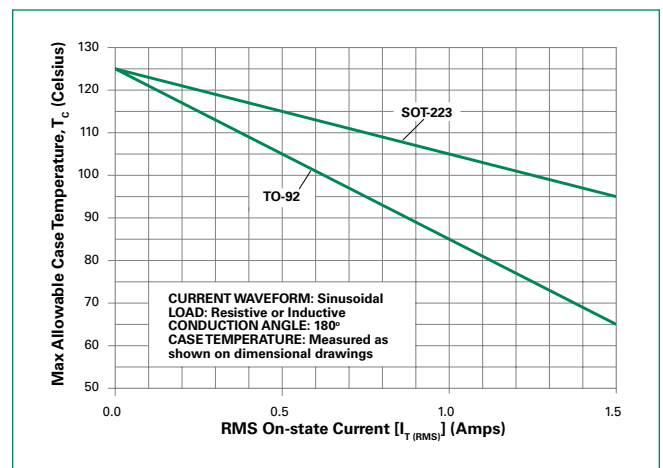
**Figure 4: On-State Current vs. On-State Voltage (Typical)**



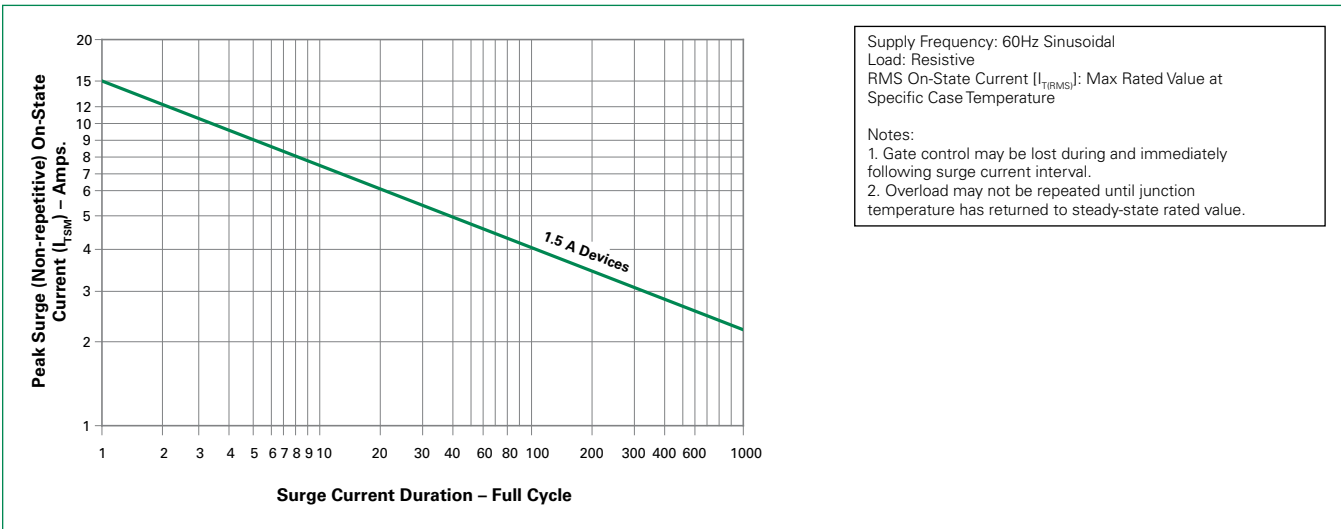
**Figure 5: Power Dissipation (Typical) vs. RMS On-State Current**



**Figure 6: Maximum Allowable Case Temperature vs. On-State Current**

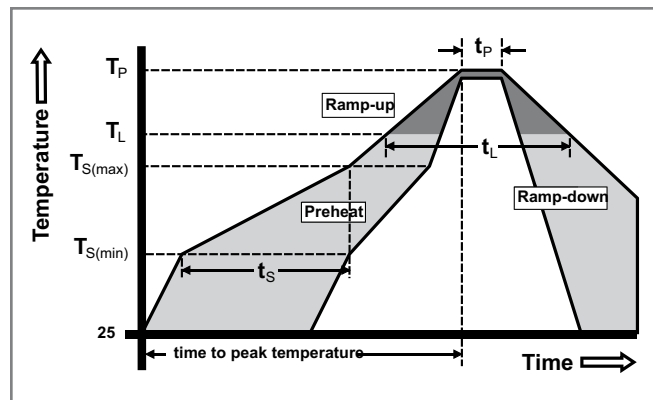


**Figure 7: Surge Peak On-State Current vs. Number of Cycles**



**Soldering Parameters**

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min (T <sub>s(min)</sub> )	150°C
	- Temperature Max (T <sub>s(max)</sub> )	200°C
	- Time (min to max) (t <sub>s</sub> )	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T <sub>L</sub> ) to peak		5°C/second max
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T <sub>L</sub> ) (Liquidus)	217°C
	- Time (min to max) (t <sub>s</sub> )	60 – 150 seconds
Peak Temperature (T <sub>p</sub> )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T <sub>p</sub> )		8 minutes Max.
Do not exceed		280°C



### Physical Specifications

<b>Terminal Finish</b>	100% Matte Tin-plated.
<b>Body Material</b>	UL recognized epoxy meeting flammability classification 94V-0.
<b>Lead Material</b>	Copper Alloy

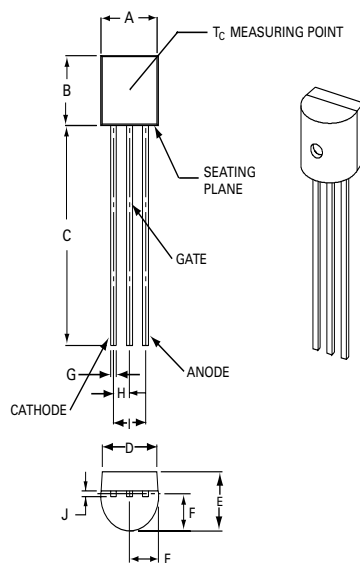
### Design Considerations

Careful selection of the correct device for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the device rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

### Environmental Specifications

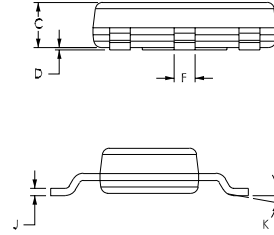
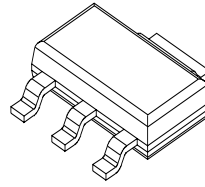
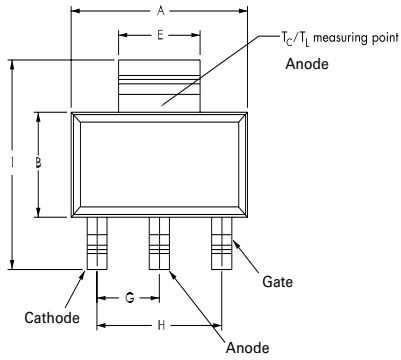
Test	Specifications and Conditions
<b>AC Blocking</b>	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 125°C for 1008 hours
<b>Temperature Cycling</b>	MIL-STD-750, M-1051, 100 cycles; -40°C to +150°C; 15-min dwell-time
<b>Temperature/Humidity</b>	EIA / JEDEC, JESD22-A101 1008 hours; 320V - DC: 85°C; 85% rel humidity
<b>High Temp Storage</b>	MIL-STD-750, M-1031, 1008 hours; 150°C
<b>Low-Temp Storage</b>	1008 hours; -40°C
<b>Resistance to Solder Heat</b>	MIL-STD-750 Method 2031
<b>Solderability</b>	ANSI/J-STD-002, category 3, Test A
<b>Lead Bend</b>	MIL-STD-750, M-2036 Cond E

### Dimensions — TO-92 (E Package)

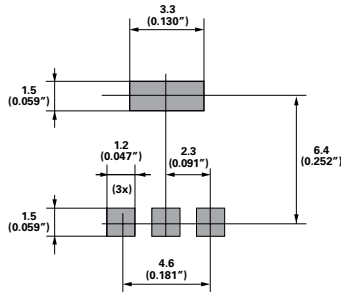


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.175	0.205	4.450	5.200
B	0.170	0.210	4.320	5.330
C	0.500	—	12.700	—
D	0.135	—	3.430	—
E	0.125	0.165	3.180	4.190
F	0.080	0.105	2.040	2.660
G	0.016	0.021	0.407	0.533
H	0.045	0.055	1.150	1.390
I	0.095	0.105	2.420	2.660
J	0.015	0.020	0.380	0.500

**Dimensions – SOT-223**



Pad Layout for SOT-223



Dimensions in Millimeters (Inches)

Dimensions	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.248	0.256	0.264	6.30	6.50	6.70
B	0.130	0.138	0.146	3.30	3.50	3.70
C	—	—	0.071	—	—	1.80
D	0.001	—	0.004	0.02	—	0.10
E	0.114	0.118	0.124	2.90	3.00	3.15
F	0.024	0.027	0.034	0.60	0.70	0.85
G	—	0.090	—	—	2.30	—
H	—	0.181	—	—	4.60	—
I	0.264	0.276	0.287	6.70	7.00	7.30
J	0.009	0.010	0.014	0.24	0.26	0.35
K	10° MAX					

**Product Selector**

Part Number	Voltage		Gate Sensitivity	Package
	400V	600V		
S402ES	X	—	200µA	TO-92
S602ES	—	X	200µA	TO-92
S402TS	X	—	200µA	SOT-223
S602TS	—	X	200µA	SOT-223

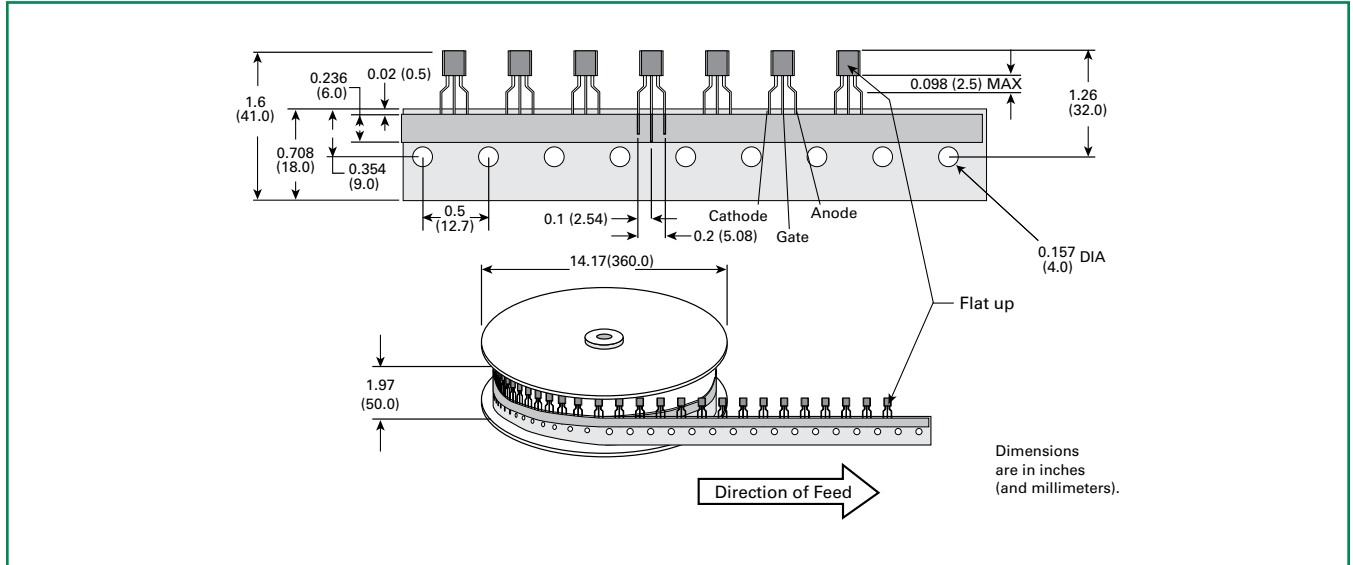
**Packing Options**

Part Number	Marking	Weight	Packing Mode	Base Quantity
Sx02ES	Sx02ES	0.217 g	Bulk	2500
Sx02ESAP	Sx02ES	0.217 g	Ammo Pack	2000
Sx02ESRP	Sx02ES	0.217 g	Tape & Reel	2000
Sx02TSRP	Sx02TS	0.120 g	Tape & Reel	1000

Note: x = voltage

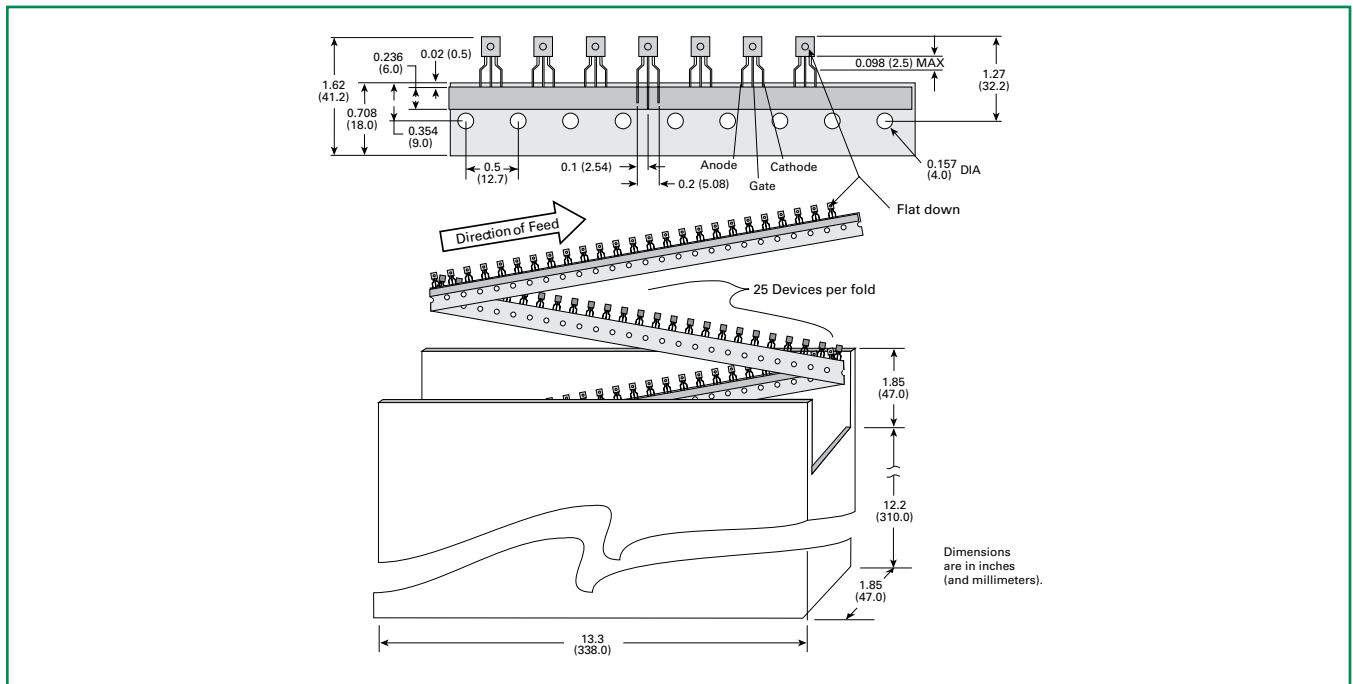
**TO-92 (3-lead) Reel Pack (RP) Radial Leaded Specifications**

Meets all EIA-468-C Standards



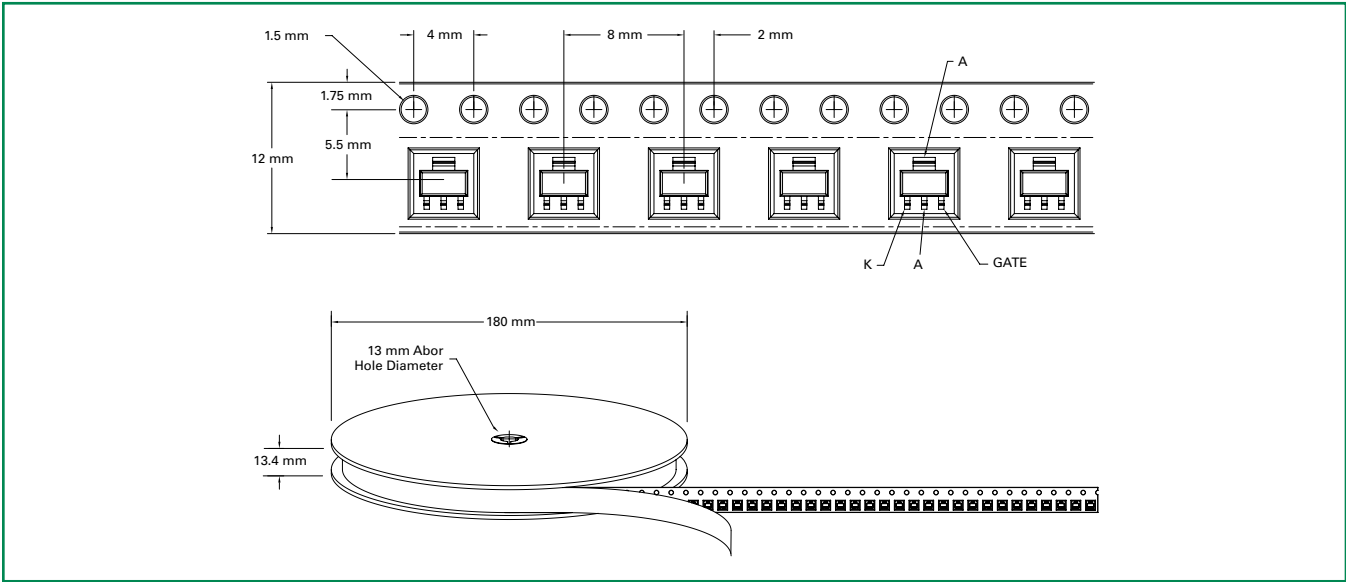
**TO-92 (3-lead) Ammo Pack (AP) Radial Leaded Specifications**

Meets all EIA-468-C Standards

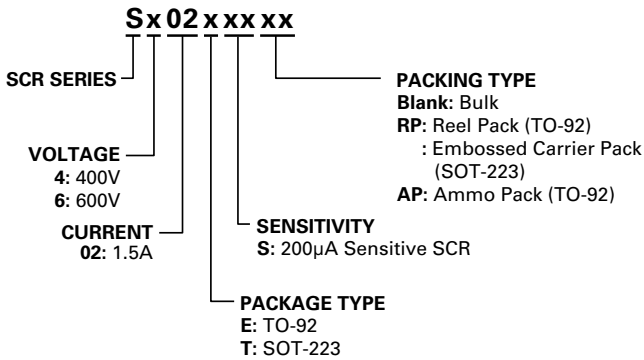




**SOT-223 Reel Pack (RP) Specifications**



**Part Numbering System**



**Part Marking System**

